

#### PCN#20190807004.1 Qualification of a new Green Mold Compound material for selected Devices Change Notification / Sample Request

#### PCN re-issue to replace the previous PCN letter.

Date:August 19, 2019To:TOKYO ELECTRON DEVICE (DSTR) PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The proposed first ship date is indicated on page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (<u>PCN\_ww\_admin\_team@list.ti.com</u>).

Sincerely,

PCN Team SC Business Services

#### 20190807004 Attachment: 1

#### **Products Affected:**

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

#### DEVICE

TL431CLP TL431CLPR TL431ACLPM

#### **CUSTOMER PART NUMBER**

null null null

Technical details of this Product Change follow on the next page(s).

PCN Number:		20190807004.1				<b>PCN Date:</b> Aug 19, 2019					
				n Mold c	lold compound material for selected Devices						
Customer Contact:		PCN Ma	nager_	De	pt:	Quality Se	rvic	es	;		
Proposed 1 <sup>st</sup> Ship Date: Nov19, 20			019	9 Estimated Sample Availability:			le	Provided upon Request			
Change Type:											
			_	Design				Wafer Bump Site			
			=	Data Sheet				Wafer Bump Material			
					Part number change				Wafer Bump Process Wafer Fab Site		
			-	Test Site			$\square$	Wafer Fab Materials			
	racking/shipping/	Labeling		Testr	Test Process			$\exists$	Wafer Fab Process		
PCN Details											
Desc	cription of Chang	je:									
Texas Instruments is pleased to announce the qualification of a new green Mold compound material for the devices list below as follows:											
Grou	ıp 1:										
					(	Current			New		
	Mold compoun	d mate	rial	401	0025	A1 (non-Gr	een	)	402042101 (Green)		
	Marking Difference				YMLLLLS XXXXX TI YM = YEAR MONTH DATE CODE LLLL = ASSEMBLY LOT CODE X = DEVICE NAME S = ASSEMBLY SITE CODE				YMLLLLS XXXXX TI <u>G3</u> YM = YEAR MONTH DATE CODE LLLL = ASSEMBLY LOT CODE X = DEVICE NAME S = ASSEMBLY SITE CODE G3 = ECAT VALUE		
Grou	ın 2:										
Groc					Current				New		
	Mold compoun	d mate	rial	4	4020024A1 (Green)				402042101 (Green)		
Deer	· ·		-			(					
Reason for Change: Current mold compound material is being discontinued by supplier. ROHS compliance.											
Anti	cipated impact o	n Fit, F	orm, F	unctior	ı, Qu	ality or Re	liat	oilit	/ (positive / negativ	e):	
None											
Anticipated impact on Material Declaration											
Char	No Impact to the Material Declarati		prod relea obta mate with	Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained from the <u>TI Eco-Info website</u> . There is no impact to the material meeting current regulatory compliance requirements with this PCN change.							
Changes to product identification resulting from this PCN:											

<b>Group 1 Device:</b> Sample product shipping label (not actual product label) The "G3" designator indicates Pb-Free/Green product with a terminal finish of Matte Sn						
TEXAS INSTRUMENTS MADE IN: Malaysia 2DC: 2Q: MSL 2 /260C/1 YEAR SEAL MSL 1 /235C/UNLIM 03/29 OPT: ITEM: 39 LBL: 5A (L)T0:17	06 A 3512 317 USA MYS					
Product Affected: Group 1						
LP2950-50LPRE3	TL1431CLPR	TL431ACLPR	TL431CLPR			
TL1431CLP	TL1431CLP TL431ACLP					
TL1431CLPME3TL431ACLPMTL431CLPM						
Product Affected: Group 2						
BQ2022ALPR						

# **Qualification Report**

Approve Date 10-Jul-2019

## **Qualification Results**

Data Displayed as: Number of lots / Total sample size / Total failed

Туре	Test Name / Condition	Duration	Qual Device: BQ2022ALPR	Qual Device: LP2950-50LPRE3	Qual Device: <u>TL1431CLP</u>
ED	Electrical Characterization	Per Datasheet Parameters	-	-	1/30/0
FLAM	Flammability	Method A - UL94 V-0	-	-	3/15/0
HAST	Biased HAST 130C/85%RH	96 Hours	-	-	3/231/0
HTSL	High Temp. Storage Bake, 170 C	420 Hours	-	-	3/231/0
MQ	Manufacturability (Assembly)	(per mfg. Site specification)	3/Pass	3/Pass	3/Pass
PD	Physical Dimensions	(per mechanical drawing)	-	-	3/15/0
PKG	Solder Heat, 260C	10 seconds	-	-	3/66/0
TC	Temperature Cycle -65C/150C	500 Cycles	3/231/0	3/231/0	3/231/0
UHAST	Unbiased HAST 130C/85%RH	96 Hours	3/231/0	-	3/231/0
VM	Visual / Mechanical	(per mfg. Site specification)	Pass	-	Pass
XRAY	X-ray	(top side only)	-	3/15/0	3/15/0
YLD	FTY and Bin Summary	-	1/Pass	-	-

- QBS: Qual By Similarity

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com

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